

TPS7A41 50V 输入电压、50mA 超高电压线性稳压器

1 特性

- 宽输入电压范围：7V 至 50V
- 准确度：
 - 标称：1%
 - 整个线路、负载和温度范围内：2.5%
- 低静态电流：25 μ A
- 关断时的静态电流：4.1 μ A
- 最大输出电流：50mA
- CMOS 逻辑电平兼容的使能引脚
- 可调节输出电压范围：约为 1.175V 至 48V
- 与陶瓷电容搭配工作时保持稳定：
 - 输入电容： $\geq 1\mu$ F
 - 输出电容： $\geq 4.7\mu$ F
- 压降电压：290mV
- 内置限流和热关断保护
- 封装方式：高散热性能的微型小外形尺寸封装 (MSOP)-8 PowerPAD™
- 工作温度范围：-40°C 至 125°C

2 应用

- 由工业用总线（具有高电压瞬态）供电的微处理器、微控制器
- 工业自动化
- 电信基础设施
- 车用
- 发光二极管 (LED) 照明
- 偏置电源

3 说明

TPS7A41 器件是一款能够耐受超高电压的线性稳压器，不仅融合了耐热增强型封装 (MSOP-8) 的优势，还能够承受持续直流电压或最高达 50V 的瞬态输入电压。

TPS7A41 与任何高于 4.7 μ F 的输出电容以及高于 1 μ F 的输入电容搭配使用时均可保持稳定（过热和浪涌保护）。鉴于这款器件的封装 (MSOP-8) 小巧且可能使用的输出电容也较小，因此实现起来只需占用非常小的电路板空间。此外，TPS7A41 还提供了一个与标准 CMOS 逻辑兼容的使能引脚 (EN)，用于使能低电流关断模式。

TPS7A41 具有热关断和电流限制功能，以便在故障情况下保护系统。MSOP-8 封装的工作温度范围为 $T_J = -40^\circ\text{C}$ 至 125°C 。

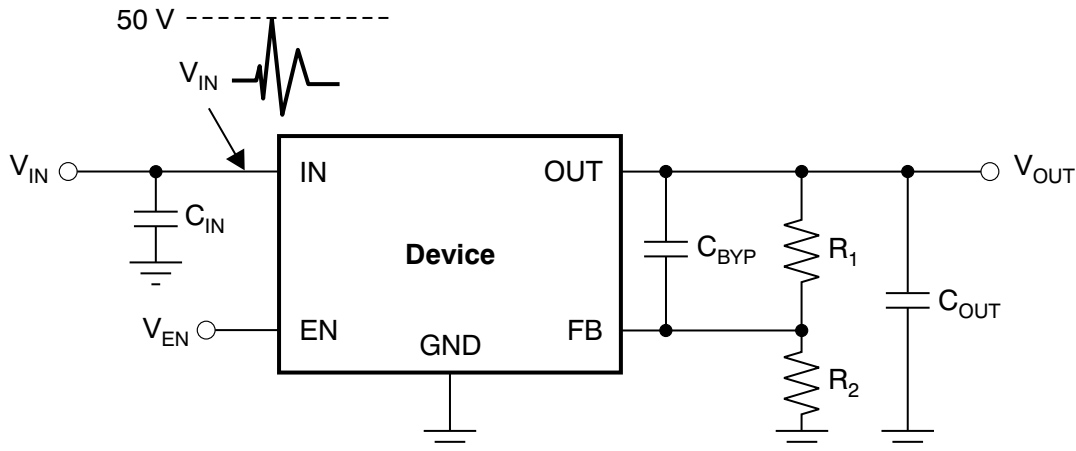
此外，TPS7A41 器件非常适合在电信和工业应用中利用中间电压轨生成低压电源；该器件不但能够提供一个充分稳压的电压轨，而且能够承受超高的快速电压瞬变并在其间保持稳压状态。这些功能相当于一套更为简单且经济高效的电气浪涌保护电路，因此受到各类应用的使用。

器件信息⁽¹⁾

器件型号	封装	封装尺寸（标称值）
TPS7A41	HVSSOP (8)	3.00mm x 3.00mm

(1) 要了解所有可用封装，请见数据表末尾的可订购产品附录。

典型应用图



目录

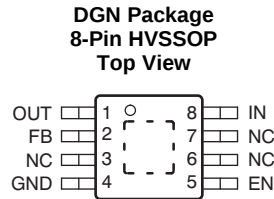
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4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Original (December 2011) to Revision A	Page
• 已添加 ESD 额定值表，特性 描述部分，器件功能模式，应用和 实施部分，电源相关建议部分，布局部分，器件和文档支持部分以及机械、封装和可订购信息部分。	1
• Changed maximum <i>Recommended Operation Conditions</i> values for VIN, VOUT, and VEN.	4

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
OUT	1	O	Regulator output. A capacitor greater than 4.7 μ F must be tied from this pin to ground to assure stability.
FB	2	I	This pin is the input to the control-loop error amplifier. It is used to set the output voltage of the device.
NC	3	—	Not internally connected. This pin must either be left open or tied to GND.
	6		
	7		
GND	4	—	Ground
EN	5	I	This pin turns the regulator on or off. If $V_{EN} \geq V_{EN_HI}$ the regulator is enabled. If $V_{EN} \leq V_{EN_LO}$, the regulator is disabled. If not used, the EN pin can be connected to IN. Make sure that $V_{EN} \leq V_{IN}$ at all times.
IN	8	I	Input supply
PowerPAD	—	—	Solder to printed-circuit-board (PCB) to enhance thermal performance. NOTE: The PowerPAD is internally connected to GND. Although it can be left floating, it is highly recommended to connect the PowerPAD to the GND plane.

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted).⁽¹⁾

		MIN	MAX	UNIT
Voltage	IN pin to GND pin	–0.3	55	V
	OUT pin to GND pin	–0.3	55	V
	OUT pin to IN pin	–55	0.3	V
	FB pin to GND pin	–0.3	2	V
	FB pin to IN pin	–55	0.3	V
	EN pin to IN pin	–55	0.3	V
	EN pin to GND pin	–0.3	55	V
Current	Peak output	Internally limited		
Temperature	Operating junction temperature, T_J	–40	125	°C
	Storage, T_{stg}	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated is not implied. Exposure to absolute-maximum rated conditions for extended periods may affect device reliability.

TPS7A41

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6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating junction temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
VIN	7		50	V
VOUT	1.161		48	V
VEN	0		50	V
IOUT	0		50	mA

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS7A41	UNIT
		DGN (HVSSOP)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	66.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	54.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	38.1	°C/W
ψ_{JT}	Junction-to-top characterization parameter	2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	37.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	15.5	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

At $T_J = -40^{\circ}\text{C}$ to 125°C , $V_{IN} = V_{OUT(NOM)} + 2\text{ V}$ or $V_{IN} = 7\text{ V}$ (whichever is greater), $V_{EN} = V_{IN}$, $I_{OUT} = 100\text{ }\mu\text{A}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{OUT} = 4.7\text{ }\mu\text{F}$, and FB tied to OUT, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IN}	Input voltage range		7		50	V
V_{REF}	Internal reference	$T_J = 25^{\circ}\text{C}$, $V_{FB} = V_{REF}$, $V_{IN} = 9\text{ V}$, $I_{OUT} = 25\text{ mA}$	1.161	1.173	1.185	V
V_{OUT}	Output voltage range ⁽¹⁾	$V_{IN} \geq V_{OUT(NOM)} + 2\text{ V}$	V_{REF}		48	V
	Nominal accuracy	$T_J = 25^{\circ}\text{C}$, $V_{IN} = 9\text{ V}$, $I_{OUT} = 25\text{ mA}$	–1		1	% V_{OUT}
	Overall accuracy	$V_{OUT(NOM)} + 2\text{ V} \leq V_{IN} \leq 24\text{ V}$ ⁽²⁾ $100\text{ }\mu\text{A} \leq I_{OUT} \leq 50\text{ mA}$	–2.5		2.5	% V_{OUT}
$\Delta V_{O(\Delta V_I)}$	Line regulation	$7\text{ V} \leq V_{IN} \leq 50\text{ V}$		0.03		% V_{OUT}
$\Delta V_{O(\Delta V_L)}$	Load regulation	$100\text{ }\mu\text{A} \leq I_{OUT} \leq 50\text{ mA}$		0.31		% V_{OUT}
V_{DO}	Dropout voltage	$V_{IN} = 17\text{ V}$, $V_{OUT(NOM)} = 18\text{ V}$, $I_{OUT} = 20\text{ mA}$		290		mV
		$V_{IN} = 17\text{ V}$, $V_{OUT(NOM)} = 18\text{ V}$, $I_{OUT} = 50\text{ mA}$		0.78	1.3	V
I_{LIM}	Current limit	$V_{OUT} = 90\% V_{OUT(NOM)}$, $V_{IN} = 7\text{ V}$, $T_J \leq 85^{\circ}\text{C}$	51	117	200	mA
		$V_{OUT} = 90\% V_{OUT(NOM)}$, $V_{IN} = 9\text{ V}$	51	128	200	mA
I_{GND}	Ground current	$7\text{ V} \leq V_{IN} \leq 50\text{ V}$, $I_{OUT} = 0\text{ mA}$		25	65	μA
		$I_{OUT} = 50\text{ mA}$		25		μA
I_{SHDN}	Shutdown supply current	$V_{EN} = 0.4\text{ V}$		4.1	20	μA
I_{FB}	Feedback current ⁽³⁾		–0.1	0.01	0.1	μA
I_{EN}	Enable current	$7\text{ V} \leq V_{IN} \leq 50\text{ V}$, $V_{IN} = V_{EN}$		0.02	1	μA
V_{EN_HI}	Enable high-level voltage		1.5		V_{IN}	V
V_{EN_LO}	Enable low-level voltage		0		0.4	V
V_{NOISE}	Output noise voltage	$V_{IN} = 12\text{ V}$, $V_{OUT(NOM)} = V_{REF}$, $C_{OUT} = 10\text{ }\mu\text{F}$, BW = 10 Hz to 100 kHz		58		μV_{RMS}
		$V_{IN} = 12\text{ V}$, $V_{OUT(NOM)} = 5\text{ V}$, $C_{OUT} = 10\text{ }\mu\text{F}$, C_{BYP} ⁽⁴⁾ = 10 nF, BW = 10 Hz to 100 kHz		73		μV_{RMS}
PSRR	Power-supply rejection ratio	$V_{IN} = 12\text{ V}$, $V_{OUT(NOM)} = 5\text{ V}$, $C_{OUT} = 10\text{ }\mu\text{F}$, C_{BYP} ⁽⁴⁾ = 10 nF, $f = 100\text{ Hz}$		65		dB
T_{SD}	Thermal shutdown temperature	Shutdown, temperature increasing		170		$^{\circ}\text{C}$
		Reset, temperature decreasing		150		$^{\circ}\text{C}$
T_J	Operating junction temperature range		–40		125	$^{\circ}\text{C}$

- (1) To ensure stability at no-load conditions, a current from the feedback resistive network greater than or equal to $10\text{ }\mu\text{A}$ is required.
- (2) Maximum input voltage is limited to 24 V because of the package power dissipation limitations at full load ($P \approx (V_{IN} - V_{OUT}) \times I_{OUT} = (24\text{ V} - V_{REF}) \times 50\text{ mA} \approx 1.14\text{ W}$). The device is capable of sourcing a maximum current of 50 mA at higher input voltages as long as the power dissipated is within the thermal limits of the package plus any external heatsinking.
- (3) $I_{FB} > 0$ flows out of the device.
- (4) C_{BYP} refers to a bypass capacitor connected to the FB and OUT pins.

6.6 Dissipation Ratings

BOARD	PACKAGE	$R_{\theta JA}$	$R_{\theta JC}$	DERATING FACTOR ABOVE $T_A = 25^{\circ}\text{C}$	$T_A \leq 25^{\circ}\text{C}$ POWER RATING	$T_A = 70^{\circ}\text{C}$ POWER RATING	$T_A = 85^{\circ}\text{C}$ POWER RATING
High-K ⁽¹⁾	DGN	55.9 $^{\circ}\text{C/W}$	8.47 $^{\circ}\text{C/W}$	16.6 mW/ $^{\circ}\text{C}$	1.83 W	1.08 W	0.833 W

- (1) The JEDEC High-K (2s2p) board design used to derive this data was a 3-inch x 3-inch multilayer board with 2-ounce internal power and ground planes and 2-ounce copper traces on top and bottom of the board.

6.7 Typical Characteristics

At $T_J = -40^\circ\text{C}$ to 125°C , $V_{IN} = V_{OUT(NOM)} + 2\text{ V}$ or $V_{IN} = 9\text{ V}$ (whichever is greater), $V_{EN} = V_{IN}$, $I_{OUT} = 100\text{ }\mu\text{A}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{OUT} = 4.7\text{ }\mu\text{F}$, and FB tied to OUT, unless otherwise noted.

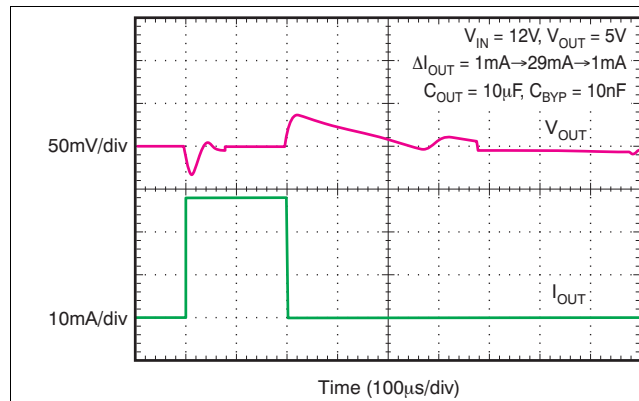


Figure 1. Load Transient Response

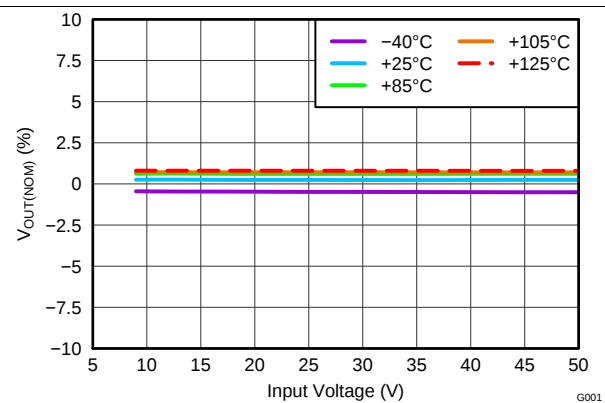


Figure 2. Line Regulation

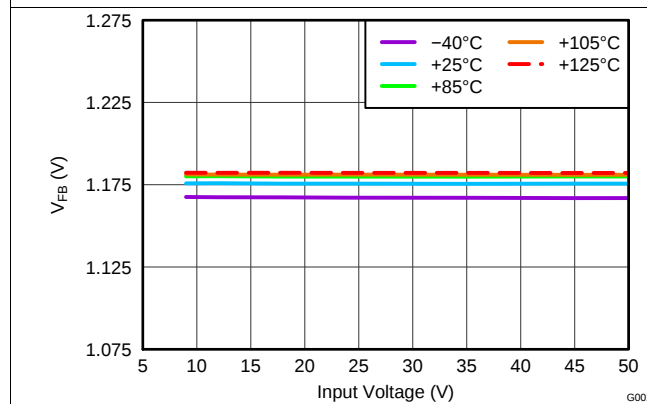


Figure 3. Feedback Voltage

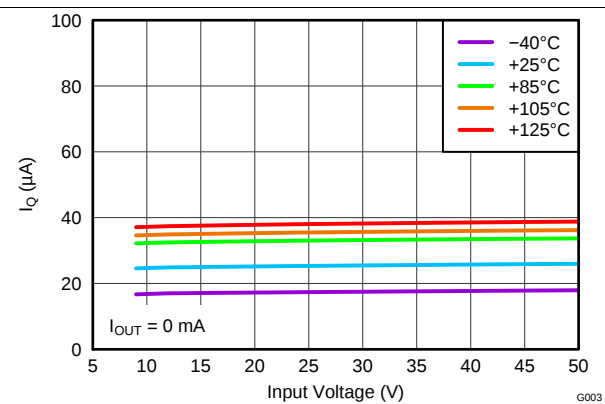


Figure 4. Quiescent Current vs Input Voltage

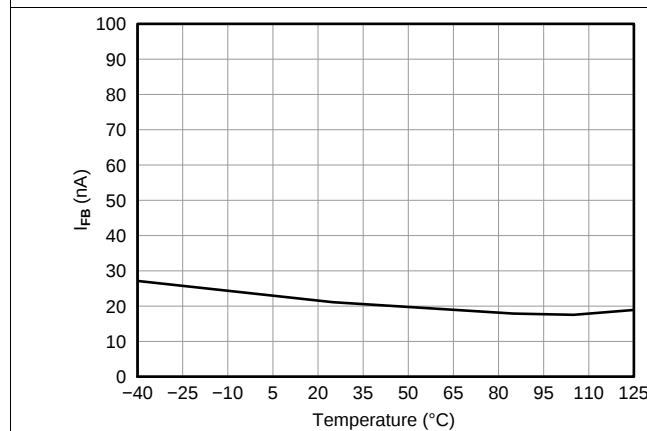


Figure 5. Feedback Current

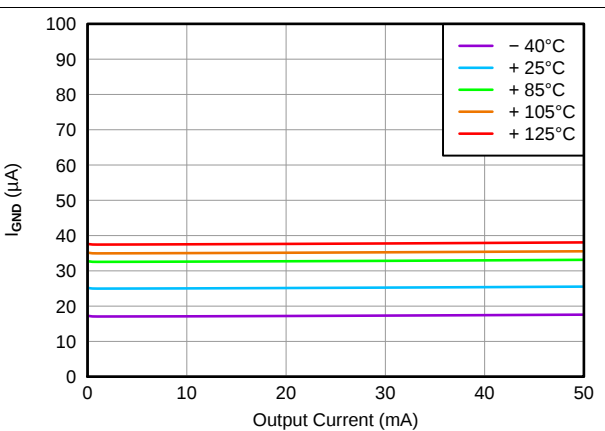


Figure 6. Ground Current

Typical Characteristics (continued)

At $T_J = -40^\circ\text{C}$ to 125°C , $V_{IN} = V_{OUT(NOM)} + 2\text{ V}$ or $V_{IN} = 9\text{ V}$ (whichever is greater), $V_{EN} = V_{IN}$, $I_{OUT} = 100\text{ }\mu\text{A}$, $C_{IN} = 1\text{ }\mu\text{F}$, $C_{OUT} = 4.7\text{ }\mu\text{F}$, and FB tied to OUT, unless otherwise noted.

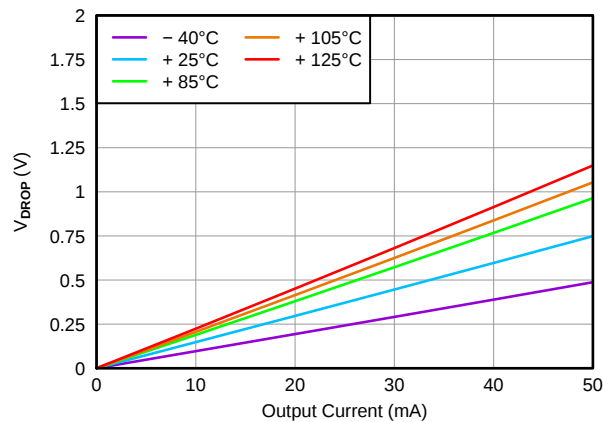


Figure 7. Dropout Voltage

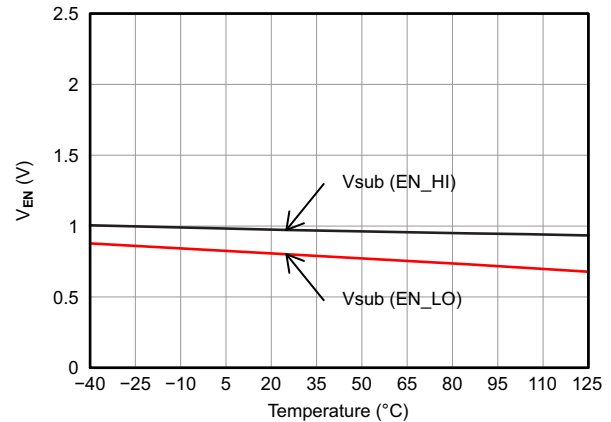


Figure 8. Enable Threshold Voltage

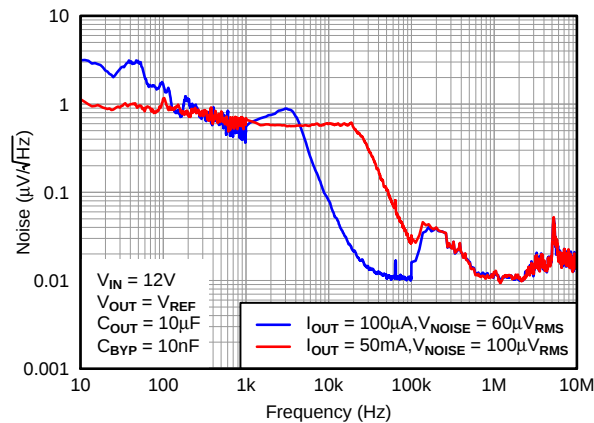


Figure 9. Output Spectral Noise Density

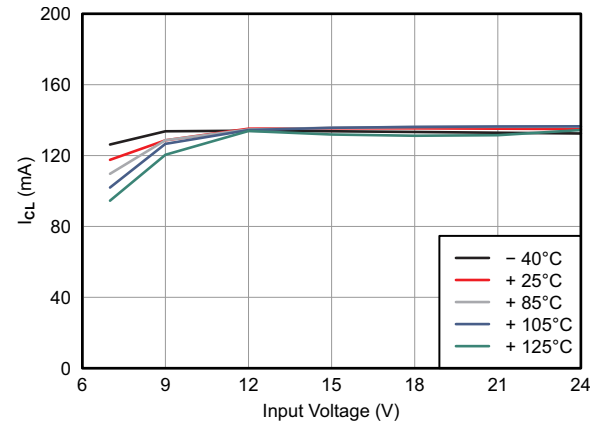


Figure 10. Current Limit

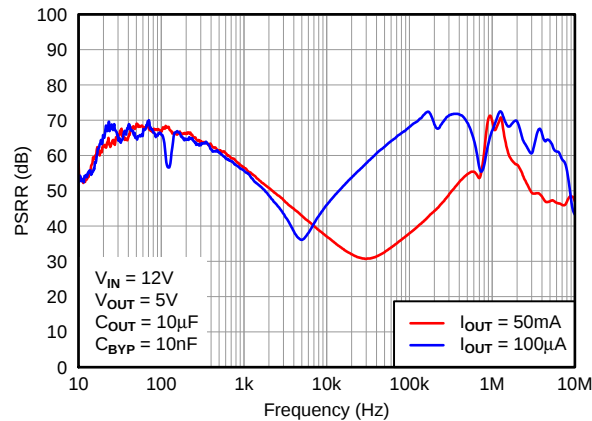


Figure 11. Power-Supply Rejection Ratio

7 Detailed Description

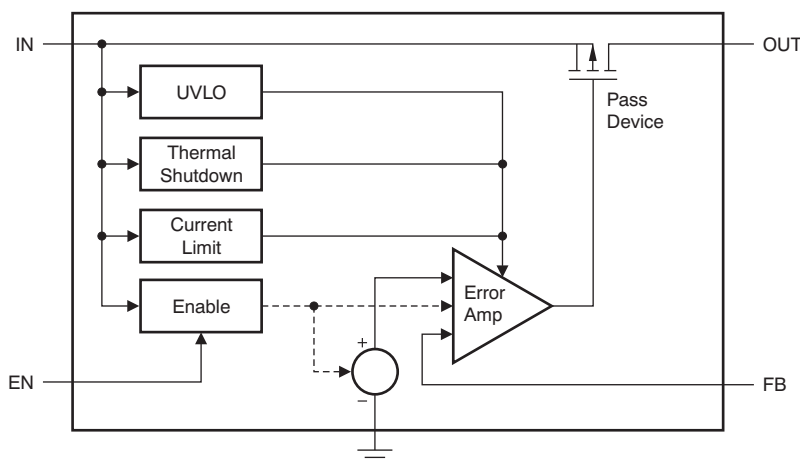
7.1 Overview

The TPS7A4101 belongs to a new generation of linear regulators that use an innovative BiCMOS process technology to achieve very high maximum input and output voltages.

This process not only allows the TPS7A4101 to maintain regulation during very fast high-voltage transients up to 50 V, but it also allows the TPS7A4101 to regulate from a continuous high-voltage input rail. Unlike other regulators created using bipolar technology, the TPS7A4101 ground current is also constant over its output current range, resulting in increased efficiency and lower power consumption.

These features, combined with a high thermal performance MSOP-8 PowerPAD package, make this device ideal for industrial and telecom applications.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Enable Pin Operation

The TPS7A4101 provides an enable pin (EN) feature that turns on the regulator when $V_{EN} > 1.5\text{ V}$.

7.3.2 Thermal Protection

Thermal protection disables the output when the junction temperature rises to approximately 170°C, allowing the device to cool. When the junction temperature cools to approximately 150°C, the output circuitry is enabled. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the dissipation of the regulator, protecting it from damage as a result of overheating.

Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heatsink. For reliable operation, limit junction temperature to a maximum of 125°C. To estimate the margin of safety in a complete design (including heatsink), increase the ambient temperature until the thermal protection is triggered; use worst-case loads and signal conditions. For good reliability, trigger thermal protection at least 35°C above the maximum expected ambient condition of your particular application. This configuration produces a worst-case junction temperature of 125°C at the highest expected ambient temperature and worst-case load.

The internal protection circuitry of the TPS7A41 device has been designed to protect against overload conditions. The protection circuitry was not intended to replace proper heatsinking. Continuously running the TPS7A4001 device into thermal shutdown degrades device reliability.

7.4 Device Functional Modes

7.4.1 Normal Operation

The device regulates to the nominal output voltage under the following conditions:

- The input voltage is at least as high as $V_{IN(min)}$.
- The input voltage is greater than the nominal output voltage added to the dropout voltage.
- The enable voltage has previously exceeded the enable rising threshold voltage and has not decreased below the enable falling threshold.
- The output current is less than the current limit.
- The device junction temperature is less than the maximum specified junction temperature.

7.4.2 Dropout Operation

If the input voltage is lower than the nominal output voltage plus the specified dropout voltage, but all other conditions are met for normal operation, the device operates in dropout mode. In this mode of operation, the output voltage is the same as the input voltage minus the dropout voltage. The transient performance of the device is significantly degraded because the pass device (as a bipolar junction transistor, or BJT) is in saturation and no longer controls the current through the LDO. Line or load transients in dropout can result in large output voltage deviations.

7.4.3 Disabled

The device is disabled under the following conditions:

- The enable voltage is less than the enable falling threshold voltage or has not yet exceeded the enable rising threshold.
- The device junction temperature is greater than the thermal shutdown temperature.

[Table 1](#) lists the conditions that lead to the different modes of operation.

Table 1. Device Functional Mode Comparison

OPERATING MODE	PARAMETER			
	V_{IN}	V_{EN}	I_{OUT}	T_J
Normal mode	$V_{IN} > V_{OUT(nom)} + V_{DO}$ and $V_{IN} > V_{IN(min)}$	$V_{EN} > V_{EN_HI}$	$I_{OUT} < I_{LIM}$	$T_J < 125^{\circ}C$
Dropout mode	$V_{IN(min)} < V_{IN} < V_{OUT(nom)} + V_{DO}$	$V_{EN} > V_{EN_HI}$	—	$T_J < 125^{\circ}C$
Disabled mode (any true condition disables the device)	—	$V_{EN} < V_{EN_LO}$	—	$T_J > 170^{\circ}C$

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

8.1.1 Adjustable Operation

The TPS7A4101 has an output voltage range of approximately 1.175 V to 48 V. The nominal output voltage of the device is set by two external resistors, as shown in [Figure 12](#).

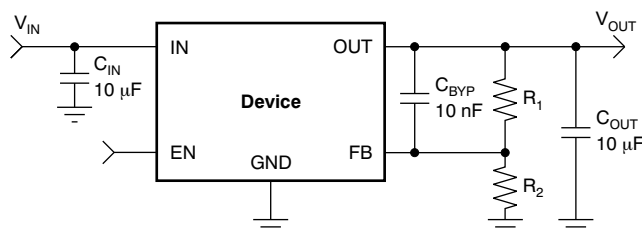


Figure 12. Adjustable Operation for Maximum AC Performance

R_1 and R_2 can be calculated for any output voltage range using the formula shown in [Equation 1](#). To ensure stability under no-load conditions, this resistive network must provide a current greater than or equal to 10 μ A.

$$R_1 = R_2 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right), \text{ where } \frac{V_{OUT}}{R_1 + R_2} \geq 10 \mu\text{A} \quad (1)$$

If greater voltage accuracy is required, take into account the output voltage offset contributions because of the feedback pin current and use 0.1% tolerance resistors.

8.1.2 Transient Voltage Protection

One of the primary applications of the TPS7A4101 is to provide transient voltage protection to sensitive circuitry that may be damaged in the presence of high-voltage spikes.

This transient voltage protection can be more cost-effective and compact compared to topologies that use a transient voltage suppression (TVS) block.

8.2 Typical Application

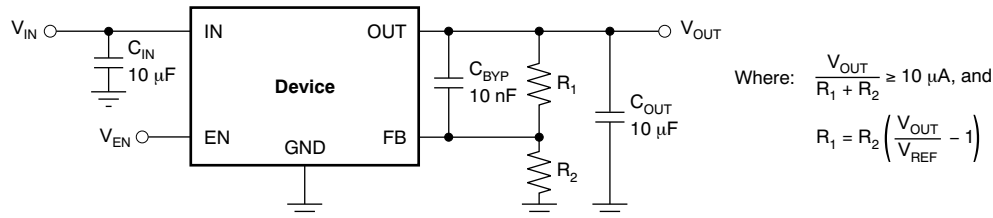


Figure 13. Example Circuit to Maximize Transient Performance

8.2.1 Design Requirements

For this design example, use the following parameters listed in [Table 2](#).

Table 2. Design Parameters

PARAMETER	VALUE
V _{IN}	12 V, with 50 V surge tolerance
V _{OUT}	5 V (ideal), 4.981 V (actual)
I _{OUT}	28 mA
Accuracy	5 %
R1, R2	162 kΩ, 49.9 kΩ

8.2.2 Detailed Design Procedure

The maximum value of total feedback resistance can be calculated to be 500 kΩ. [Equation 1](#) was used to calculate R1 and R2, and standard 1% resistors were selected to keep the accuracy within the 5% allocation. 10-µF ceramic input and output capacitors were selected, along with a 10-nF bypass capacitor for optimal AC performance.

8.2.2.1 Capacitor Recommendations

Low equivalent series resistance (ESR) capacitors should be used for the input, output, and bypass capacitors. Ceramic capacitors with X7R and X5R dielectrics are preferred. These dielectrics offer more stable characteristics. Ceramic X7R capacitors offer improved over-temperature performance, while ceramic X5R capacitors are the most cost-effective and are available in higher values.

High ESR capacitors may degrade PSRR.

8.2.2.2 Input and Output Capacitor Requirements

The TPS7A4101 high voltage linear regulator achieves stability with a minimum output capacitance of 4.7 µF and input capacitance of 1 µF; however, TI highly recommends using 10-µF output and input capacitors to maximize AC performance.

8.2.2.3 Bypass Capacitor Requirements

Although a bypass capacitor (C_{BYP}) is not needed to achieve stability, TI highly recommends using a 10-nF bypass capacitor to maximize AC performance (including line transient, noise and PSRR).

8.2.2.4 Maximum AC Performance

To maximize line transient, noise, and PSRR performance, TI recommends including 10-µF (or higher) input and output capacitors, and a 10-nF bypass capacitor; see [Figure 12](#). The solution shown delivers minimum noise levels of 58 µV_{RMS} and power-supply rejection levels above 36 dB from 10 Hz to 10 MHz.

8.2.2.5 Transient Response

As with any regulator, increasing the size of the output capacitor reduces over/undershoot magnitude but increases duration of the transient response.

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The presence of the C_{BYP} capacitor may greatly improve the TPS7A4101 line transient response, as noted in Figure 1.

8.2.3 Application Curve

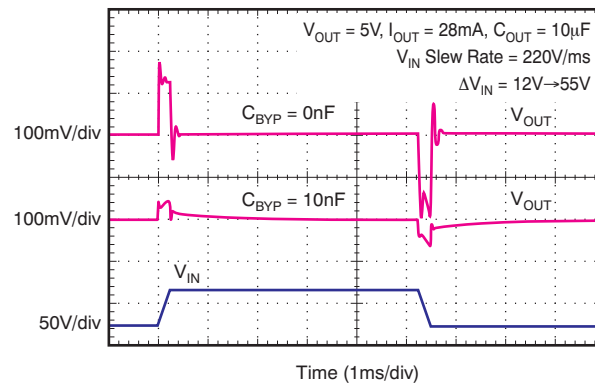


Figure 14. Line Transient Response vs C_{BYP}

9 Power Supply Recommendations

The input supply for the LDO should not exceed its recommended operating conditions (7 V to 50 V). The input voltage should provide adequate headroom for the device to have a regulated output. If the input supply is noisy, additional input capacitors with low ESR can help improve the output noise performance. The input and output supplies should also be bypassed with 10-μF capacitors located near the input and output pins. There should be no other components located between these capacitors and the pins.

10 Layout

10.1 Layout Guidelines

To improve AC performance such as PSRR, output noise, and transient response, TI recommends designing the board with separate ground planes for IN and OUT, with each ground plane connected only at the GND pin of the device. In addition, the ground connection for the output capacitor should connect directly to the GND pin of the device.

Equivalent series inductance (ESL) and ESR must be minimized to maximize performance and ensure stability. Every capacitor (C_{IN} , C_{OUT} , C_{BYP}) must be placed as close as possible to the device and on the same side of the PCB as the regulator itself.

Do not place any of the capacitors on the opposite side of the PCB from where the regulator is installed. The use of vias and long traces is strongly discouraged because they may impact system performance negatively and even cause instability.

If possible, and to ensure the maximum performance denoted in this product data sheet, use the same layout pattern used for TPS7A41 evaluation board, available at www.ti.com.

10.2 Layout Example

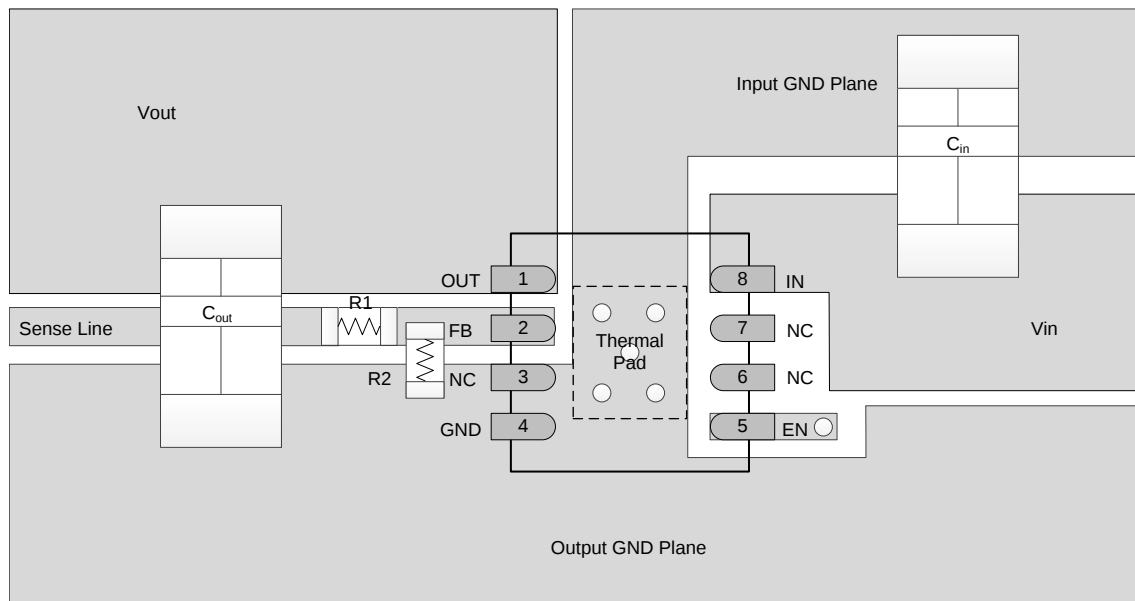


Figure 15. Recommended Layout Example

10.3 Thermal Considerations

Thermal protection disables the output when the junction temperature rises to approximately 170°C, allowing the device to cool. When the junction temperature cools to approximately 150°C, the output circuitry is enabled. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the dissipation of the regulator, protecting it from damage as a result of overheating.

Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heatsink. For reliable operation, junction temperature should be limited to a maximum of 125°C. To estimate the margin of safety in a complete design (including heatsink), increase the ambient temperature until the thermal protection is triggered; use worst-case loads and signal conditions. For good reliability, thermal protection should trigger at least 35°C above the maximum expected ambient condition of the particular application. This configuration produces a worst-case junction temperature of 125°C at the highest expected ambient temperature and worst-case load.

Thermal Considerations (continued)

The internal protection circuitry of the TPS7A4101 has been designed to protect against overload conditions. It was not intended to replace proper heatsinking. Continuously running the TPS7A4101 into thermal shutdown degrades device reliability.

10.4 Power Dissipation

The ability to remove heat from the die is different for each package type, presenting different considerations in the PCB layout. The PCB area around the device that is free of other components moves the heat from the device to the ambient air. Performance data for JEDEC low- and high-K boards are given in the [Dissipation Ratings](#). Using heavier copper increases the effectiveness in removing heat from the device. The addition of plated through-holes to heat dissipating layers also improves the heatsink effectiveness.

Power dissipation depends on input voltage and load conditions. Power dissipation (P_D) is equal to the product of the output current times the voltage drop across the output pass element, as shown in [Equation 2](#):

$$P_D = (V_{IN} - V_{OUT}) I_{OUT} \quad (2)$$

10.5 Package Mounting

Solder pad footprint recommendations for the TPS7A4101 are available at [机械、封装和可订购信息](#) and at www.ti.com.

11 器件和文档支持

11.1 社区资源

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11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS7A4101DGNR	ACTIVE	MSOP- PowerPAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	SBB	Samples
TPS7A4101DGNT	ACTIVE	MSOP- PowerPAD	DGN	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	SBB	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS7A4101DGNR	MSOP-Power PAD	DGN	8	2500	330.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1
TPS7A4101DGNT	MSOP-Power PAD	DGN	8	250	180.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

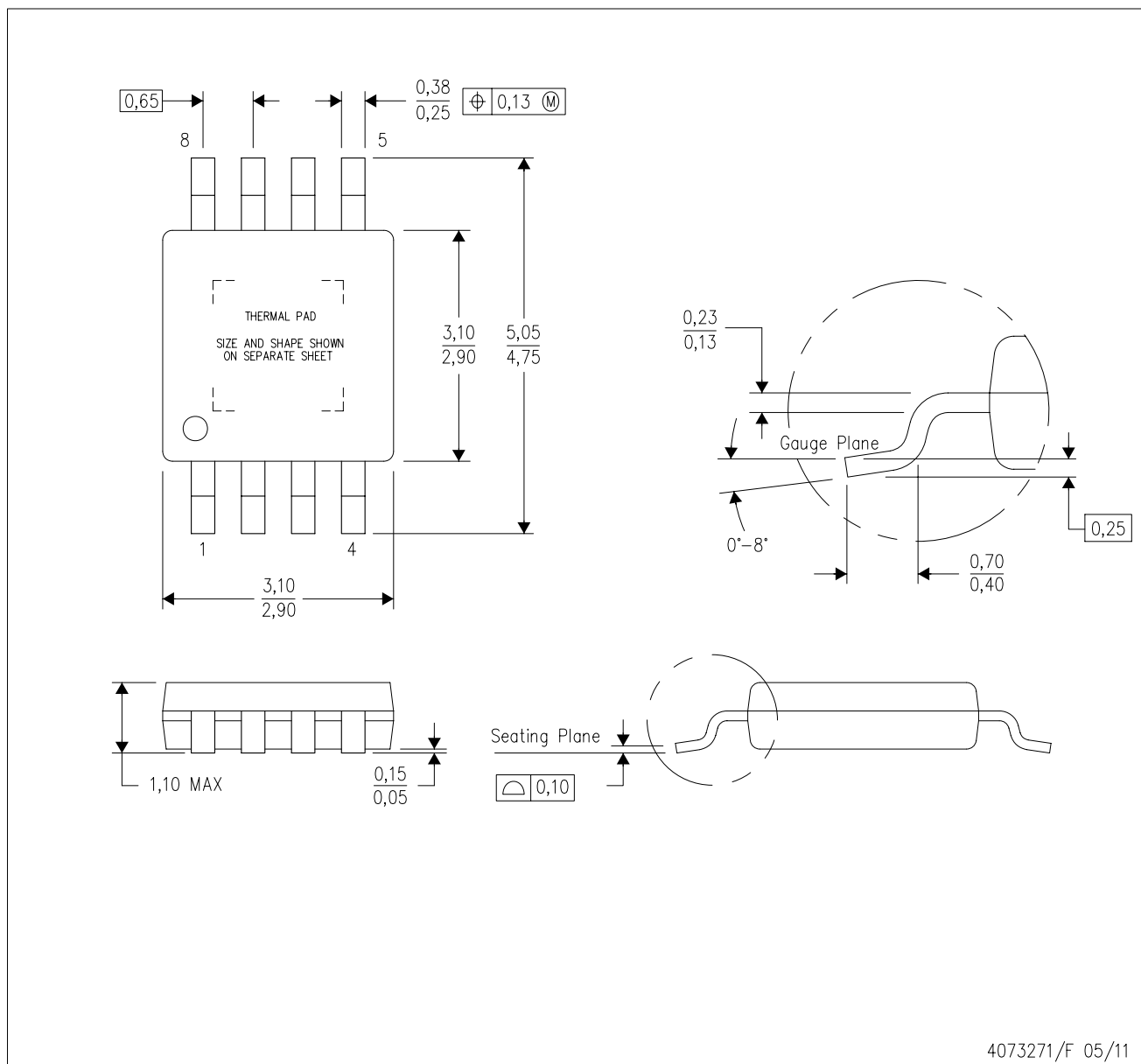


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS7A4101DGNR	MSOP-PowerPAD	DGN	8	2500	346.0	346.0	35.0
TPS7A4101DGNT	MSOP-PowerPAD	DGN	8	250	203.0	203.0	35.0

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Falls within JEDEC MO-187 variation AA-T

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DGN (S-PDSO-G8)

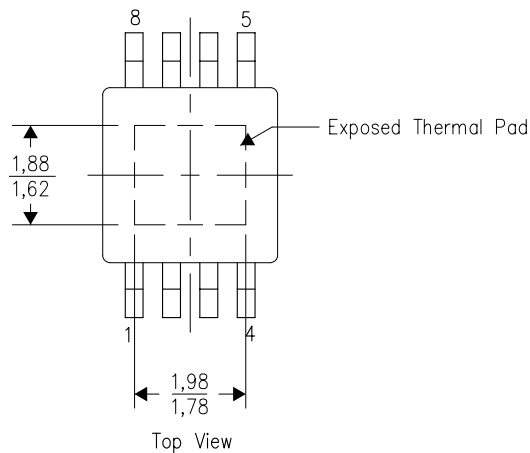
PowerPAD™ PLASTIC SMALL OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

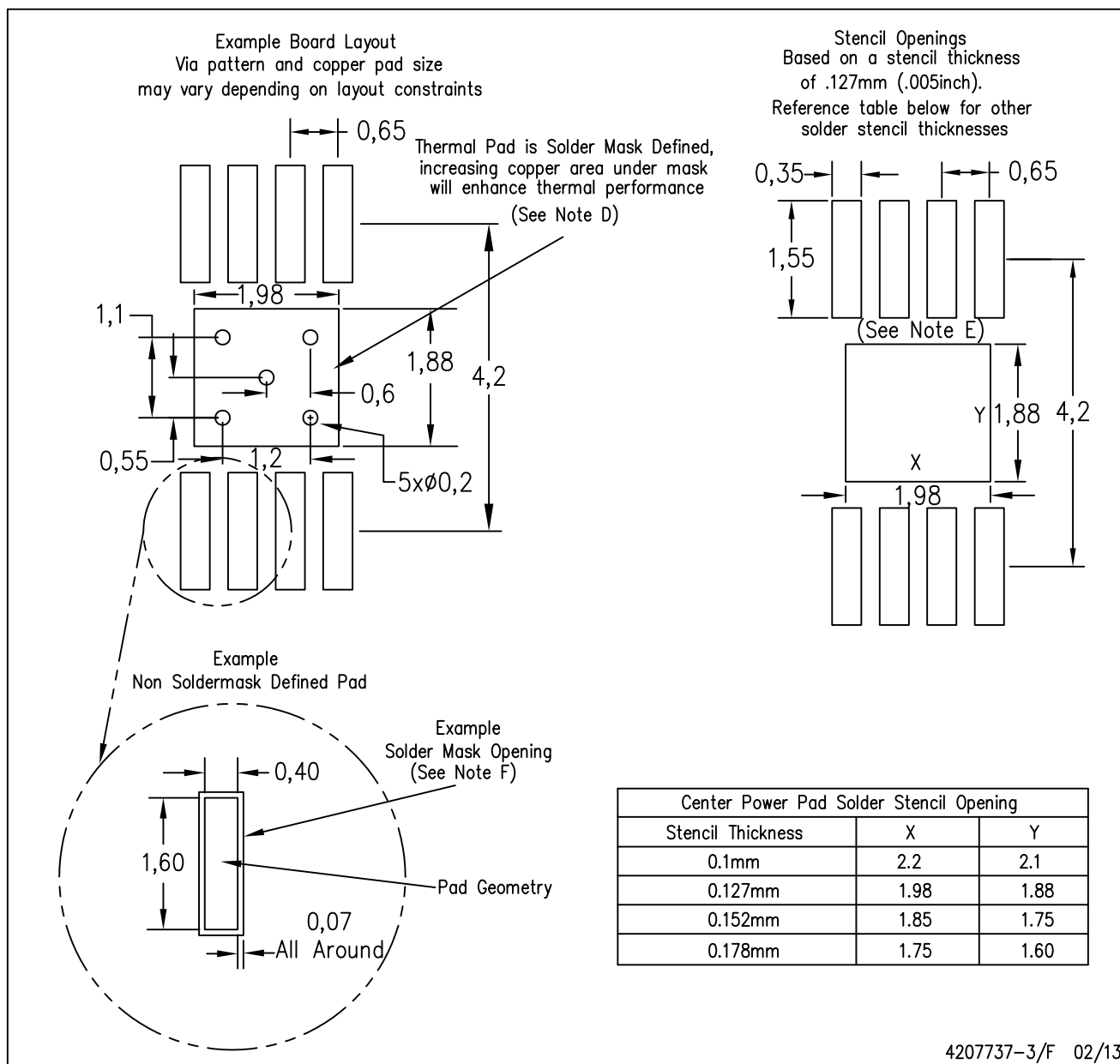
4206323-3/1 12/11

NOTE: All linear dimensions are in millimeters

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DGN (R-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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